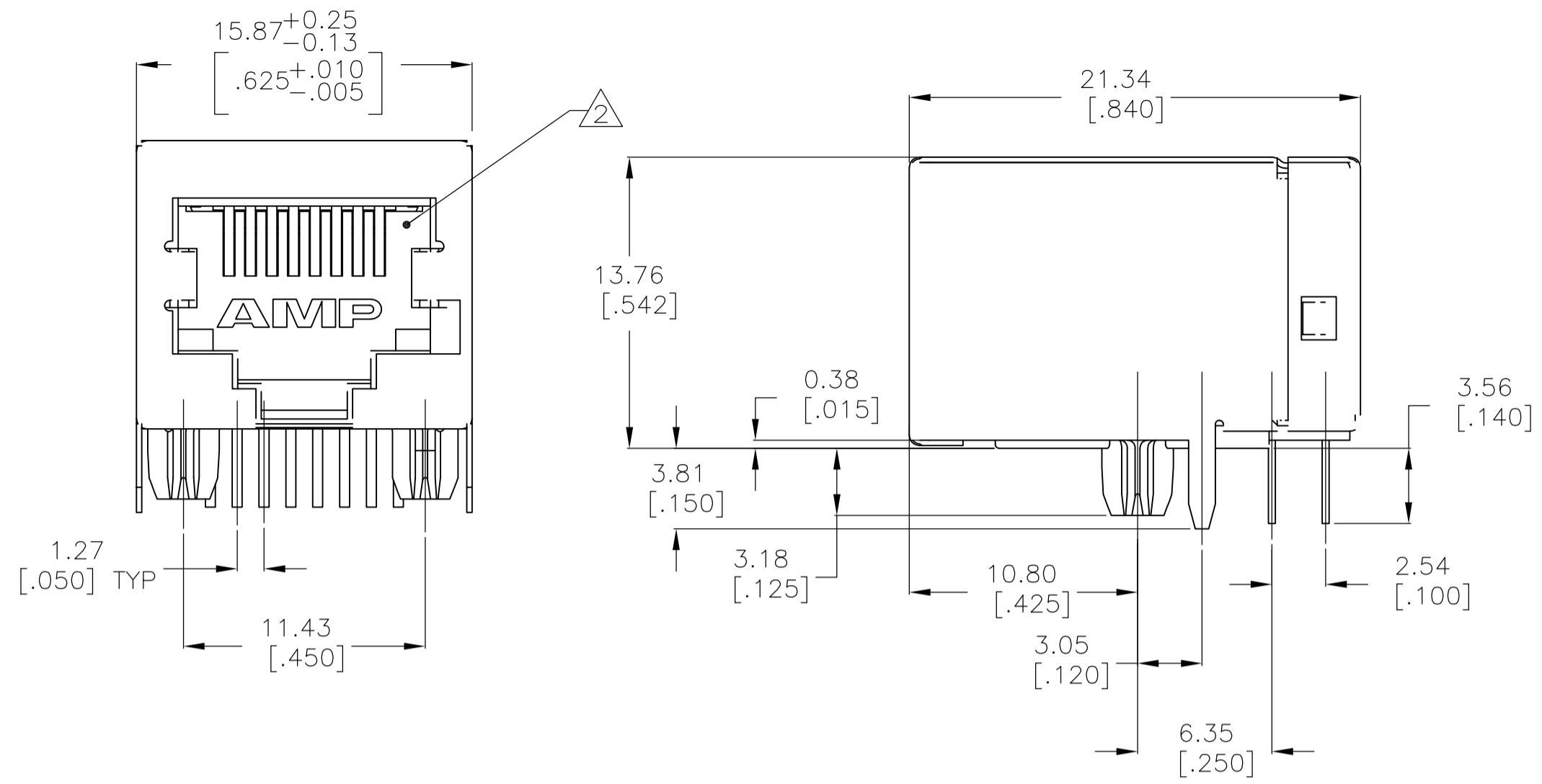
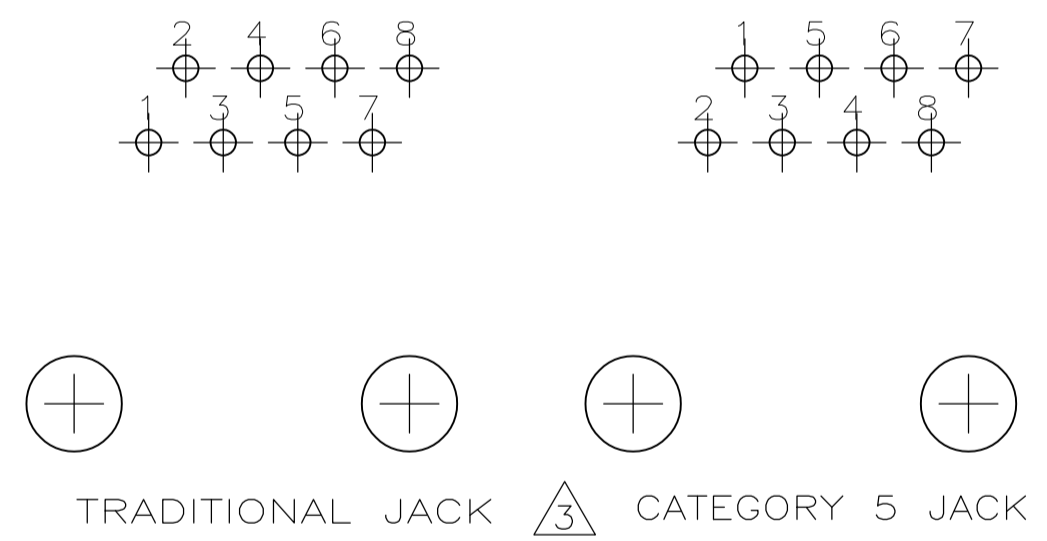
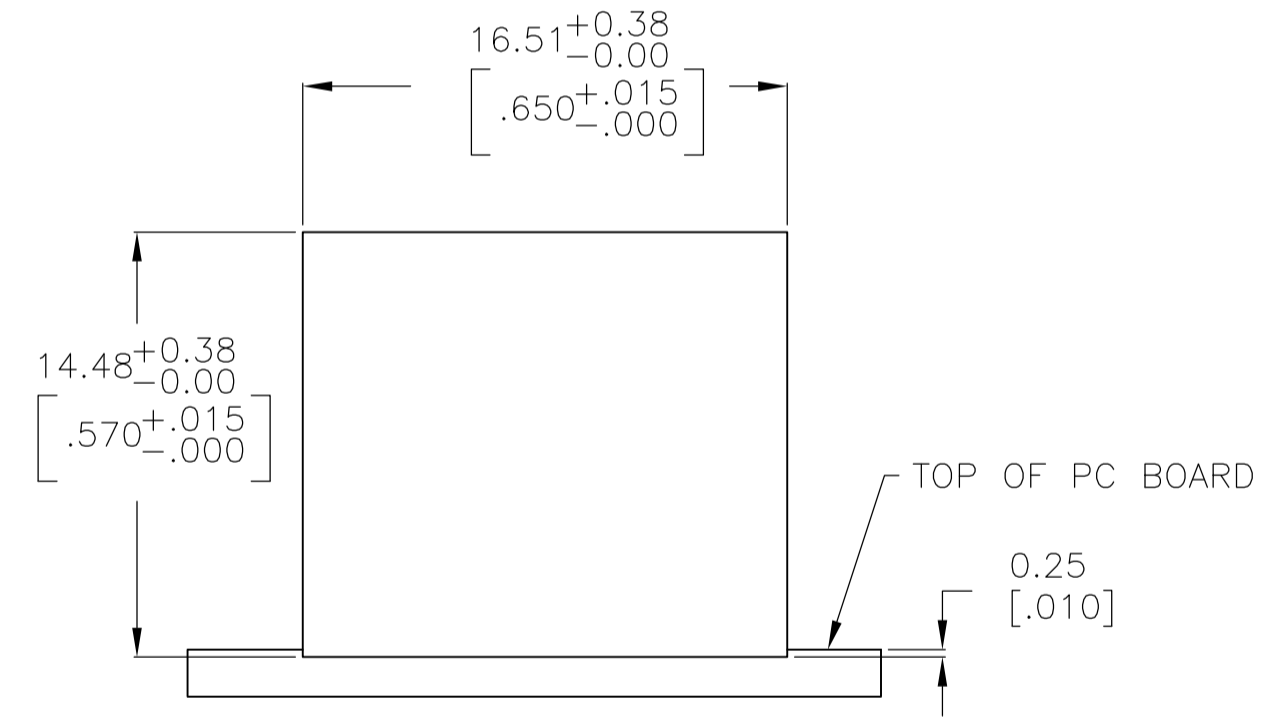
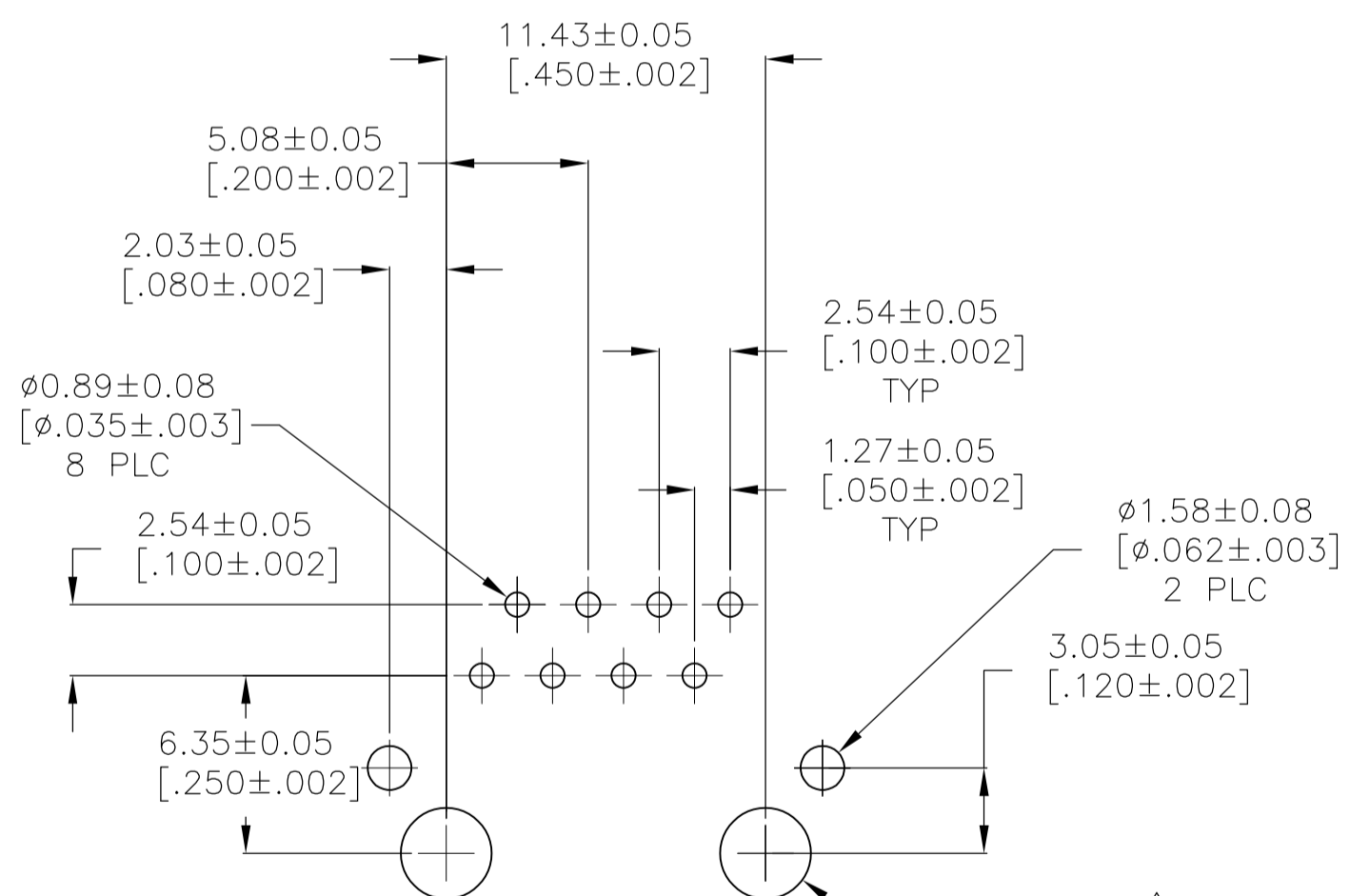


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LOC	DIST	REVISIONS					
AA	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
		D1		REVISED PER ECO-11-005033	26MAR11	RK	HMR
		E		ECO-11-019003	19SEP11	JJ	MQW



- MATERIAL: HOUSING HTN, BLACK.
 TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELDS - 0.254[.010] THICK COPPER ALLOY PLATED WITH 1.27µm[.000050] MINIMUM NICKEL AND 2.03 µm [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- CAUTION: CATEGORY 5 JACK SOLDER TAIL POSITIONS DO NOT FOLLOW SAME NUMBER SEQUENCE AS THAT OF TRADITIONAL JACKS.
- USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- SHIELD MATERIAL: PHOS BRONZE.



SUGGESTED PC BOARD LAYOUT
COMPONENT SIDE

SUGGESTED PANEL CUTOUT
SCALE 4:1

6	BLACK	5558342-3
5	GRAY	5558342-2
	BLACK	5558342-1
	HOUSING COLOR	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	01JUNE2005	TE Connectivity	
		CHK	01JUNE2005	TE Connectivity	
		APVD	01JUNE2005	TE Connectivity	
		PRODUCT SPEC	108-1163-2	TE Connectivity	
		APPLICATION SPEC	114-2048	TE Connectivity	
MATERIAL		FINISH	WEIGHT	SCALE	RESTRICTED TO
SEE NOTE 1		SEE NOTE 1	-	A2 00779 C=5558342	-
		CUSTOMER DRAWING		SCALE	REV
				4:1	E

5558342